

CHIP BEAD

FEATURES

- Suit for SMT.
- Shape, dimension and electrical properties accord with EIA standard.
- Superior solder ability and resistance to soldering heat.
- Ideal for wave or reflow soldering.



HOW TO ORDER

CBG	160808	V	050	T
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Product symbol	Dimension		Material Code	(Ω) impedance	Packaging Style	
CBG	160808	1.6x0.8x0.8	V	56N=0.056	B	Bulk
CBH	201209	2.0x1.2x0.92.0x1.2x1.2	U	2R2=2.2	T	Tape & Reel
			J			
CBY	321611	3.2x1.6x1.6	X	270=27x10 ¹		

DIMENSIONS

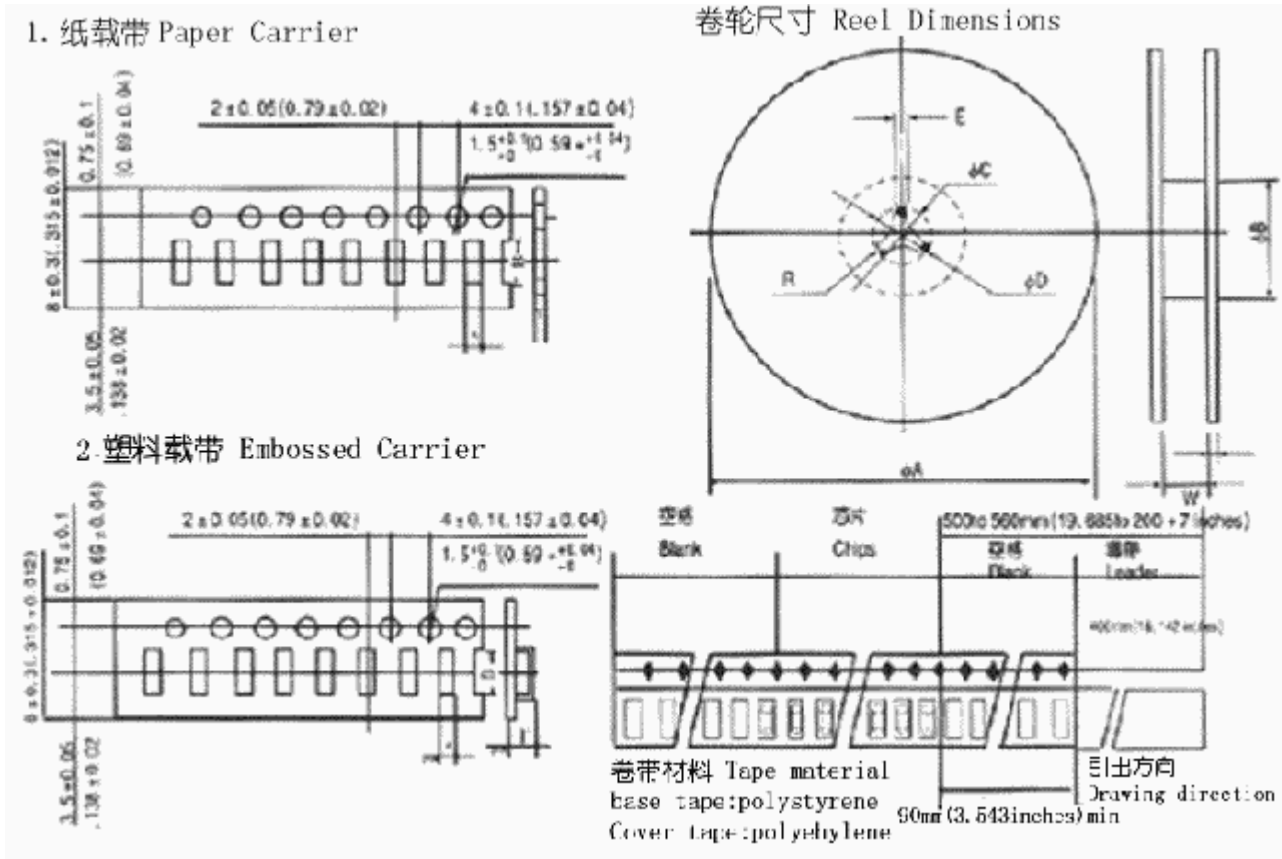
	SIZE	Length	Width	Thickness	Termination Width
	160808	1.6±0.15 (0.063±0.06)	0.8±0.15 (0.31±0.06)	0.8±0.15 (0.31±0.06)	0.3±0.2 (0.012±0.008)
201209 201212	2.0+0.3/-0.1 (0.79±0.12/-0.1)	1.25±0.2 (0.049±0.008)	0.8±0.2 (0.33±0.008) 1.25±0.2 (0.049±0.008)	0.5±0.3 (0.020±0.012)	
321611	3.2±0.2 (0.126±0.008)	1.6±0.2 (0.063±0.008)	1.1±0.3 (0.043±0.012)	0.5±0.3 (0.020±0.012)	

CHIP BEAD

PACKAGING

Packaging style: Bulk, Tape and Reel

Paper Carrier Dimensions



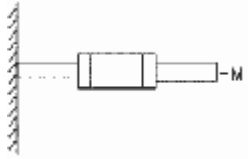
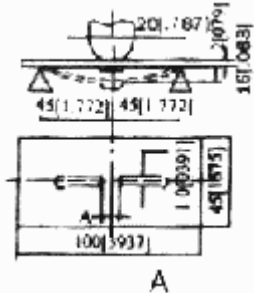
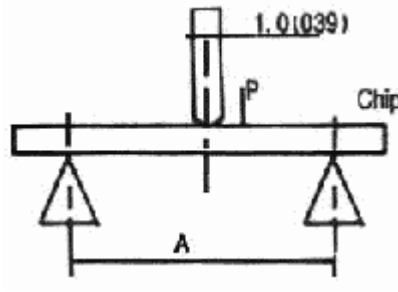
REEL PACKAGING QUANTITY

Code	1608		2012		3216		
A	1.1(.048)		1.45(0.57)		1.9(0.075)		
B	1.8(0.07)		2.3(0.91)		3.5(.138)		
T	0.8(.031)	1.2(.048)	0.85(.033)	1.25(.049)	0.6(.024)	0.85(.033)	1.1(.043)
max	0.95(.037)	1.5(.059)	0.95(.037)	1.5(.059)	0.75(.029)	0.95(.037)	1.37(.053)
Fig No	1	2	1	2	1	1	2
pcs/reel	4000pcs		4000pcs		3000pcs		

A	178+2(7.00+0.079)
B	60+1(2.36+0.039)
C	130+0.5(5.12+0.02)
D	210+0.8(8.27+0.031)
E	20+0.5(0.79+0.02)
W	10.0+1.0(0.39+0.039)
T	2.0+0.5(0.079+0.02)
R	1.0(0.039)

CHIP BEAD

RELIABILITY TEST AND TEST CONDITIONS

Item	Specifications	Test Methods												
Temperature Operating Ranges	-25°C~+85°C													
Storage Temperature Range	-40°C+85°C -0°C+60°C (Tape & Reel)													
Solder Ability	More than 90% of termination Should be covered with new solder	Preheat: : 120°C~+150°C for 60s Solder sn: pb=63:37 Temperature: 230°C±5°C Flux: rosin Duration: 3±1s												
Resistance to Soldering heat	More than 75% of termination Should be covered with solder	Preheat: 120°C~+150°C for 60s Solder sn: pb=63:37 Temperature: 230°C±5°C Flux: rosin Duration: 10±0.5s												
Terminal Strength	The terminal and body should be no damage	Applied specified pull strength in axial direction <table border="1"> <thead> <tr> <th>Size</th> <th>Pull Strength (N)(kg)</th> <th>Time</th> </tr> </thead> <tbody> <tr> <td>1608</td> <td>5.9(0.6)</td> <td>30±5</td> </tr> <tr> <td>2012</td> <td>9.8(1.0)</td> <td>30±5</td> </tr> <tr> <td>3216</td> <td>9.8(1.0)</td> <td>30±5</td> </tr> </tbody> </table> 	Size	Pull Strength (N)(kg)	Time	1608	5.9(0.6)	30±5	2012	9.8(1.0)	30±5	3216	9.8(1.0)	30±5
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1608	5.9(0.6)	30±5												
2012	9.8(1.0)	30±5												
3216	9.8(1.0)	30±5												
Flexure Strength	No mechanical damage should be noticed	When the board curve to 2mm(0.079 inches) <table border="1"> <tbody> <tr> <td>0.7(0.028)</td> <td>(1608)</td> </tr> <tr> <td>1.0(0.039)</td> <td>(2012)</td> </tr> <tr> <td>2.0(0.039)</td> <td>(3216)</td> </tr> </tbody> </table> Dimensions in mm (inches) 	0.7(0.028)	(1608)	1.0(0.039)	(2012)	2.0(0.039)	(3216)						
0.7(0.028)	(1608)													
1.0(0.039)	(2012)													
2.0(0.039)	(3216)													
Bending Strength	The ferrite body should not be damaged	Applied the force on the right direction <table border="1"> <thead> <tr> <th>Size</th> <th>A(mm) (inches)</th> <th>Pn (kg)</th> </tr> </thead> <tbody> <tr> <td>160808</td> <td>100(0.039)</td> <td>4.9(0.5)</td> </tr> <tr> <td>201209 201212</td> <td>1.4(0.055)</td> <td>9.8(1.0)</td> </tr> <tr> <td>321611</td> <td>2.0(0.079)</td> <td>9.8(1.0)</td> </tr> </tbody> </table> 	Size	A(mm) (inches)	Pn (kg)	160808	100(0.039)	4.9(0.5)	201209 201212	1.4(0.055)	9.8(1.0)	321611	2.0(0.079)	9.8(1.0)
Size	A(mm) (inches)	Pn (kg)												
160808	100(0.039)	4.9(0.5)												
201209 201212	1.4(0.055)	9.8(1.0)												
321611	2.0(0.079)	9.8(1.0)												
Thermal Shock (Temperature Cycling)	No mechanical damage should be noticed inductance and Q value should be within ±10% and±30% of the value respectively	Temperature:-25°C~+85°C 5cycles 30min for each												
High Temperature		Please at 80°C applied dc200mA for 500hrs and measured at ambient temperature												
Humidity Resistance		Please at 60°C 90%RH applied DC 200mA for 500hrs and measured at ambient temperature												
Drop		Drop 10 times on a concrete floor from a height of 1m												
Vibration		Frequency:10~50Hz Amplitude modulation:1.55mm Direction and time: X、Y and Z direction for 2hrs each												
Solubility Resistance		Solvent: trichloroethylene Cleaning: Ultrasonic washer Duration:3min												

CHIP BEAD

CHIP BEAD (CBG)

PRODUCT SERIES CBG 160808

Part No.	(Ω) Impedance $\pm 25\%$	(MHz) Test Frequency	(Ω) DC Resistance Max.	(mA) Rated Current Max.
CBG160808U050	5	100	0.1	300
CBG160808U070	7	100	0.1	300
CBG160808U110	11	100	0.1	300
CBG160808U190	19	100	0.1	300
CBG160808U310	31	100	0.1	300
CBG160808U600	60	100	0.2	150
CBG160808U800	80	100	0.2	150
CBG160808U121	120	100	0.4	150
CBG160808U181	180	100	0.5	150
CBG160808U301	300	100	0.6	100
CBG160808U501	500	100	0.8	100
CBG160808U601	600	100	0.8	100
CBG160808U102	1000	100	1.0	50

PRODUCT SERIES 201209 / 201212

Part No.	(Ω) Impedance $\pm 25\%$	(MHz) Test Frequency	(Ω) DC Resistance Max.	(mA) Rated Current Max.
CBG201209U070	7	100	0.1	600
CBG201209U110	11	100	0.1	600
CBG201209U190	19	100	0.2	500
CBG201209U260	26	100	0.2	500
CBG201209U310	31	100	0.2	400
CBG201209U360	36	100	0.2	400
CBG201209U660	66	100	0.2	300
CBG201209U700	70	100	0.2	300
CBG201209U800	80	100	0.2	250
CBG201209U121	120	100	0.3	200
CBG201209U151	150	100	0.3	200
CBG201209U181	180	100	0.3	200
CBG201209U221	220	100	0.4	200
CBG201209U301	300	100	0.4	200
CBG201209U501	500	100	0.5	200
CBG201209U601	600	100	0.5	200
CBG201209X751	750	100	0.6	200
CBG201209X102	1000	100	0.6	100
CBG201209X122	1200	50	0.7	50
CBG201209X152	1500	50	0.8	50
CBG201209X202	2000	50	1.0	50

PRODUC SERIES 321611

Part No.	(Ω) Impedance $\pm 25\%$	(MHz) Test Frequency	(Ω) DC Resistance Max.	(mA) Rated Current Max.
CBG321611U190	19	100	0.1	600
CBG321611U260	26	100	0.2	500
CBG321611U310	36	100	0.2	500
CBG321611U660	31	100	0.2	500
CBG321611U800	66	100	0.2	400
CBG321611U121	80	100	0.2	300
CBG321611U151	120	100	0.2	300
CBG321611U181	150	100	0.3	250
CBG321611U221	180	100	0.3	200
CBG321611U301	300	100	0.4	200
CBG321611U501	500	100	0.5	200
CBG321611U601	600	100	0.5	200
CBG321611U751	750	100	0.6	200
CBG321611X501	500	100	0.5	200
CBG321611X601	600	100	0.5	200
CBG321611X701	750	100	0.6	200
CBG321611X102	1000	100	0.6	100
CBG321611X122	1200	50	0.7	100
CBG321611X152	1500	50	0.7	100
CBG321611X202	2000	50	0.8	100
CBG321611X252	2500	50	0.9	20
CBG321611X302	3000	50	1.0	50

CHIP BEAD

FERRITE CHIP BEAD(CBY)

PRODUCT SERIES CBY 160808

Part Number	Impedance(Ω) At 100MHz	(Ω) DC Resistance Max.	(mA) Rated Current Max.
CBY160808V050	5 \pm 25%	0.20	600
CBY160808V090	9 \pm 25%	0.20	500
CBY160808V110	11 \pm 25%	0.20	500
CBY160808V190	19 \pm 25%	0.20	200
CBY160808V310	31 \pm 25%	0.30	400
CBY160808V600	60 \pm 25%	0.30	300
CBY160808V800	80 \pm 25%	0.30	300
CBY160808V121	120 \pm 25%	0.30	200
CBY160808V221	220 \pm 25%	0.30	200
CBY160808V301	300 \pm 25%	0.35	150
CBY160808V451	450 \pm 25%	0.40	150
CBY160808V601	600 \pm 25%	0.45	100
CBY160808V801	800 \pm 25%	0.50	100
CBY160808V102	1000 \pm 25%	0.60	100

PRODUCT SERIES 201209

Part Number	Impedance(Ω) At 100MHz	(Ω) DC Resistance Max.	(mA) Rated Current Max.
CBY201209V070	7 \pm 25%	0.20	600
CBY201209V110	11 \pm 25%	0.20	600
CBY201209V190	19 \pm 25%	0.20	600
CBY201209V260	26 \pm 25%	0.20	400
CBY201209V310	31 \pm 25%	0.20	400
CBY201209V700	70 \pm 25%	0.25	400
CBY201209V800	80 \pm 25%	0.25	400
CBY201209V121	120 \pm 25%	0.25	300
CBY201209V151	150 \pm 25%	0.25	300
CBY201209V221	220 \pm 25%	0.25	300
CBY201209V301	300 \pm 25%	0.30	200
CBY201209V501	500 \pm 25%	0.35	200
CBY201209V601	600 \pm 25%	0.40	200
CBY201209V801	800 \pm 25%	0.40	150
CBY201209V102	1000 \pm 25%	0.45	100

PRODUCT SERIES 321611

Part Number	Impedance(Ω) At 100MHz	(Ω) DC Resistance Max.	(mA) Rated Current Max.
CBY321611V190	19 \pm 25%	0.20	500
CBY321611V260	26 \pm 25%	0.20	500
CBY321611V310	31 \pm 25%	0.20	500
CBY321611V600	60 \pm 25%	0.30	400
CBY321611V700	70 \pm 25%	0.30	400
CBY321611V800	80 \pm 25%	0.30	400
CBY321611V900	90 \pm 25%	0.30	300
CBY321611V121	120 \pm 25%	0.30	300
CBY321611V151	150 \pm 25%	0.30	300
CBY321611V301	300 \pm 25%	0.30	300
CBY321611V501	500 \pm 25%	0.30	200
CBY321611V601	600 \pm 25%	0.30	200
CBY321611V801	800 \pm 25%	0.30	200
CBY321611V102	1000 \pm 25%	0.30	200
CBY321611V122	1200 \pm 25%(At 50MHz)	0.50	100
CBY321611V202	2000 \pm 25%(At 30MHz)	0.60	100

CHIP BEAD

CHIP BEAD (CBH)

PRODUCT SERIES

Part Number	Impedance At 100MHz	DC Resistance(Ω) Max.	Rated Current(A) Max.
CBW160808U300	30 \pm 25%	0.06	1.0
CBW201209U070	7 \pm 25%	0.03	3.0
CBW201209U110	11 \pm 25%	0.025	3.0
CBW201209U300	30 \pm 25%	0.025	3.0
CBW201209U600	60 \pm 25%	0.025	3.0
CBW201209U700	70 \pm 25%	0.025	3.0
CBW321611U190	19 \pm 25%	0.04	3.0
CBW321611U260	26 \pm 25%	0.04	3.0
CBW321611U310	31 \pm 25%	0.04	3.0
CBW321611U500	50 \pm 25%	0.03	3.0
CBW321611U600	60 \pm 25%	0.03	3.0
CBW321611U700	70 \pm 25%	0.03	3.0
CBW321611U800	80 \pm 25%	0.03	3.0
CBW321611U121	120 \pm 25%	0.02	3.0

TYPICAL CHARACTERISTICS

IZI, R, XL Frequency Typical Characteristics

